

Title (en)

RESIN-LABEL-MOUNTING DEVICE AND RESIN-LABEL-MOUNTING METHOD

Title (de)

KUNSTSTOFFETIKETTMONTAGEVORRICHTUNG UND KUNSTSTOFFETIKETTMONTAGEVERFAHREN

Title (fr)

DISPOSITIF DE MONTAGE D'ÉTIQUETTES EN RÉSINE ET PROCÉDÉ DE MONTAGE D'ÉTIQUETTES EN RÉSINE

Publication

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Application

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Abstract (en)

[origin: EP2781460A1] In the present invention, when forming a tube shape by overlapping the back end portion (2a) of a resin label (2) to the front end portion, the portion of the terminus (2aa) to which glue has not been applied is heated and cured. Glue is applied by means of a glue application means (14) to the back end portion (2a) of the resin label (2) held at a transfer drum (10), and after wrapping around a mandrel (28) and forming a tube shape by overlapping and adhering the back end portion (2a) to the front end portion, the back end portion (2a) including the portion of the terminus (2aa) to which glue has not been applied is heated by means of a heater (176) for a shorter period of time than that at which the resin label (2) welds and at a higher temperature than the heating temperature when causing shrinkage afterwards. The terminus (2aa) at which glue has not been applied of the back end portion (2a) of the resin label (2) is cured, and so there is no curling or deformation, and the appearance as a product is improved.

IPC 8 full level

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